

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: VINCENT S. CHANG, CHIA-LIN CHEN, CHI-CHUN CHEN, TZE-LIANG LEE, SHIH-CHANG CHEN, CHIEN-HAO CHEN

For: HIGH TEMPERATURE HYDROGEN ANNEALING OF A GATE INSULATOR LAYER TO INCREASE ETCHING

## SELECTIVITY BETWEEN CONDUCTIVE GATE STRUCTURE AND GATE INSULATOR LAYER

Enclosed are:						
x	3 sheets of drawing(s) - formal.					
x	An assignment of the invention to Taiwan Semiconductor Manufacturing Co.					
	An associate power of attorney Applicant claims small entity status					
	Request & Certification under 35 USC 122(b)(2)(b)(i)					
The filing fee has been calculated as shown below:						
		(Col. 1)	(Col. 2)	OTHER THAN A	OTHER THAN A SMALL ENTITY	
FOR:		NO. FILED	NO. EXTRA	RATE	FEE	
BASIC FEE		$\nearrow$	$\langle$		\$ 770.	
TOTAL CLAIMS		<b>20</b> -20=	0	x 18 =	<b>\$ 0.</b>	
INDEP	CLAIMS	3 -3=	0 ,	x 86 =	\$ 0.	
				SUB TOTAL	\$ 770.	
				ASSIGNMENT	\$40.	
				TOTAL	\$ 810.	
x	Please charge my Deposit Account No. 19-0033 in the amount of \$810. A duplicate copy of this sheet is enclosed.					
x	The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any					
overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.						
X Any additional filing fees required under 37 CFR §1.16.						
X Any patent application processing fees under 37 CFR §1.17.						
Respectfully submitted,						
	TEPHEN B. ACKERMAN, REG. NO. 37,761					
	EXPRESS MAIL CERTIFICATE					

Express Mail No. EV385357641US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant-and/or Atterney requests the date of deposit as the Filing Date.

Signature / Date